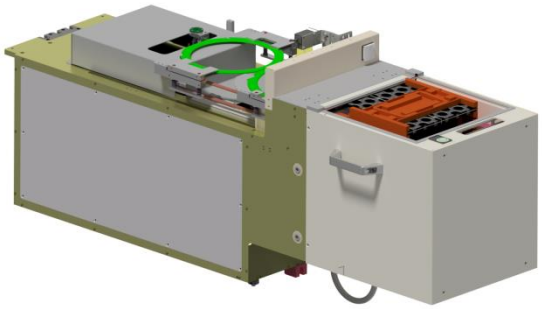
FEEDER FRAME

Input of 6“/8“ wafer frame components



The FEEDER FRAME module is used to feed components into the machine from wafer frames. It is made up of the module itself and the upstream frame lift which can be separated from the module and in which both full and empty frames can be deposited in a magazine. Full frames are fed individually to the module, positioned for removal of individual components and transported back as empty frames to the frame lift.

Product description/functions

- Frame lift at front, can be separated from the module
- Input and output of wafer frames via a magazine in the frame lift
  Manual feeding of individual wafer frames is also possible without the frame lift
- Manual insertion of magazine from above into the frame lift
- Manual removal of the magazine by pulling it upwards out of the frame lift
- Lowering of the magazine using the frame lift
- Positioning of lowermost full frame on a carriage powered by a step motor
- Components are arranged in a grid in rows and columns on the frame
- Step motor-powered needle assembly below the frame with a vertical needle, vacuum suction cup and lighting
- The component grid on the frame is illuminated from below so the camera on the axis system can ensure correct position determination
- An optional possibility is identification of substandard parts by camera
- A barcode/2D code scanner is also an option for identification of individual frames in the process
- Based on the position values, the carriage moves the frame into the correct row position above the needle assembly
- The needle assembly moves transversely relative to this along the columns and positions the needle, centring it under the respective component
- The vacuum suction cup suctions the frame film from below so that it curves slightly over the needle
- The component is suctioned from above by a Z phi axis on the axis system, pierced from below by the needle and finally removed from the frame

Options

Equipment set	Equipment set for 6“/8“ frames
Camera	Camera for identification of substandard parts

Version 11/21

Technical data

Module dimensions W/H/D [approx. mm]	340x380x360
Frame lift dimensions W/H/D [approx. mm]	340 x 930 x 515
Module weight	40 kg
Frame lift weight	30 kg
Media:	
AC	–
DC	24 / 12 V
Compressed air	6 bar
Vacuum	–
Miscellaneous	Ethernet 100 Mb

Accessories

- Wafer frame magazine 8"
- Wafer frame magazine 6"
- Code scanner

Detailed drawings

